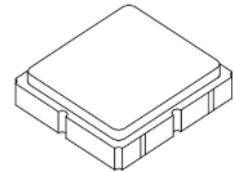


SF2008D

**930.5 MHz
SAW Filter**



SM3838-6

- *RF Filter for Pager Applications*
- *High Rejection Out of Band*
- *Complies with Directive 2002/95/EC (RoHS)*
- *Moisture Sensitivity Level: 1*

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	0	dBm
Maximum DC Voltage Between Any Two Terminals	30	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			930.5		MHz
Passband Insertion Loss, 928.5 to 932.5 MHz	IL_{MAX}				4.5	dB
Passband Amplitude Ripple, 928.5 to 932.5 MHz					2.0	dB _{P-P}
Rejection Referenced to IL_{MAX}						
400 to 880 MHz			35			dB
884.8 to 890.2 MHz			40			
906.8 to 911.2 MHz			30			
980 to 1300 MHz			35			
Operating Temperature Range	T_A		-20		+70	°C
Input Impedance at f_C			50 - j57 ohm			
Output Impedance at f_C			50 - j57 ohm			
Case Style	SM3838-6 3.8 x 3.8 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	455, <u>YWWS</u>					

Electrical Connections

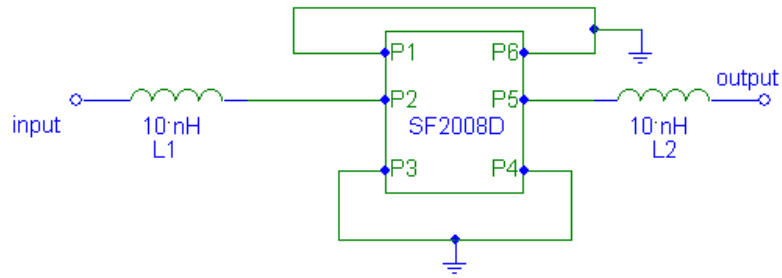
Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

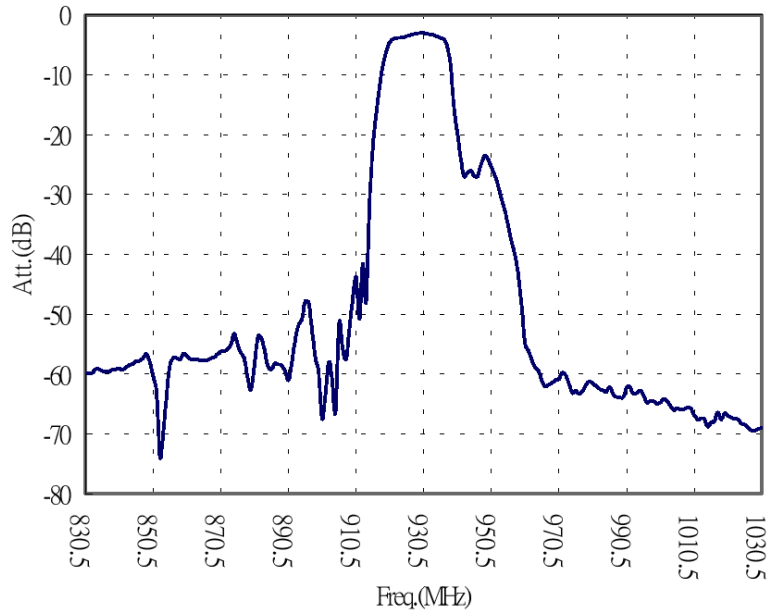
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

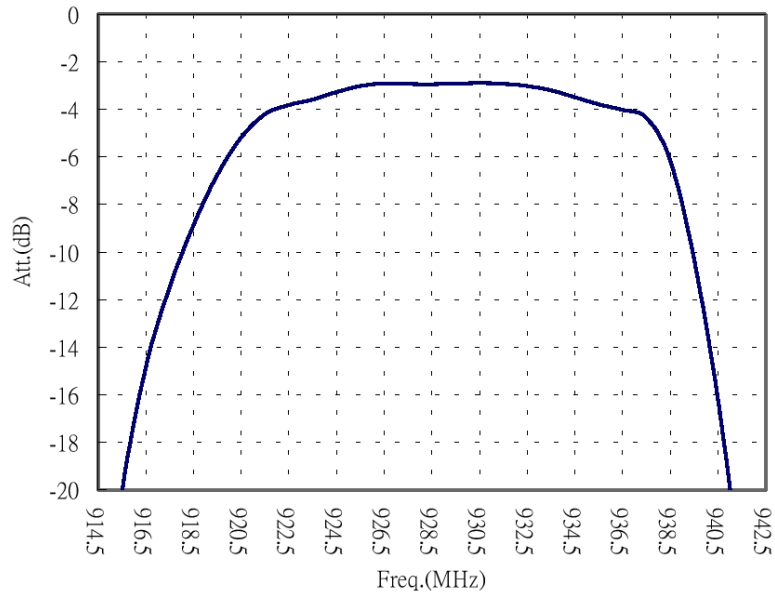
Matching Circuit



S21 Wide Span



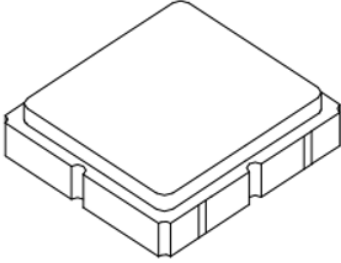
S21 Narrow Span



SM3838-6 Case

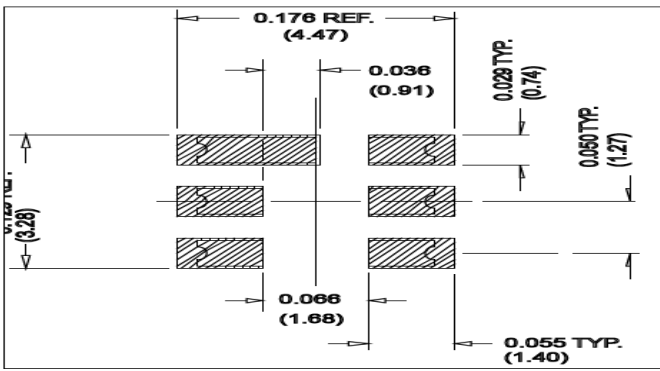
6-Terminal Ceramic Surface-Mount Case

3.8 X 3.8 mm Nominal Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.60	3.80	4.0	0.14	0.15	0.16
B	3.60	3.80	4.0	0.14	0.15	0.16
C	1.30	1.50	1.70	0.05	0.06	0.067
D	0.95	1.10	1.25	0.037	0.043	0.05
E	2.39	2.54	2.69	0.090	0.10	0.110
G	0.90	1.0	1.10	0.035	0.04	0.043
H	1.90	2.0	2.10	0.075	0.08	0.83
I	0.50	0.6	0.70	0.020	0.024	0.028
J	1.70	1.8	1.90	0.067	0.07	0.075

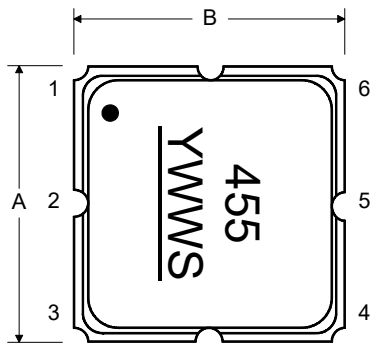
Electrical Connections		
Connection	Terminals	
Port 1	Single-ended Input	2
Port 2	Single-ended Output	5
	Ground	All others
Single-ended Operation Only		
Dot indicates Pin 1		



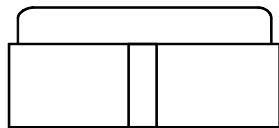
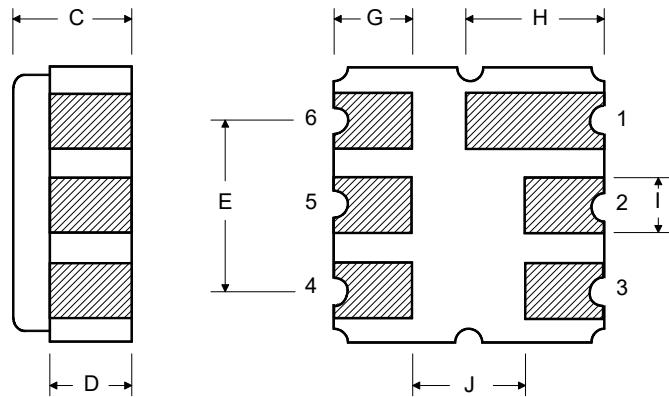
PCB Footprint

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW

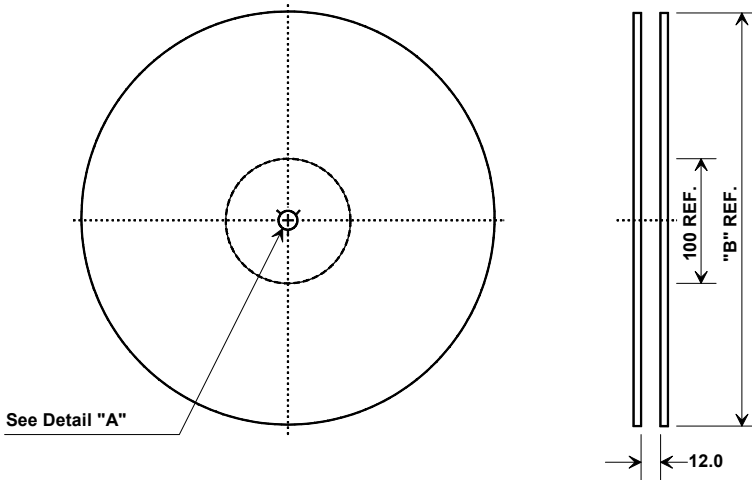


BOTTOM VIEW

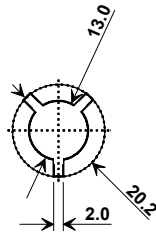


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

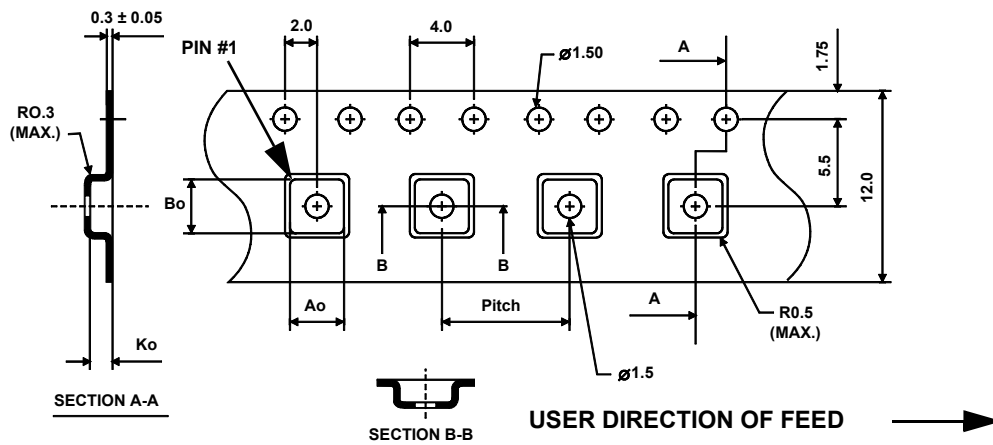


"B "		Quantity Per Reel
Inches	millimeters	
7	178	1000
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

